

SOT809-1

plastic low profile ball grid array package; 224 balls; body 17 x 17 x 1.05 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LBGA224
Package type industry code	LBGA224
Package style descriptive code	LBGA (low profile ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-192
Mounting method type	S (surface mount)
Issue date	22-5-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	16.8	-	17	17.2	mm
E	package width	16.8	-	17	17.2	mm
A	seated height	[tbd]	-	1.65	1.65	mm
A ₂	package height	0.95	-	1.05	1.2	mm
n ₂	actual quantity of termination	-	-	224	-	



2. Package outline

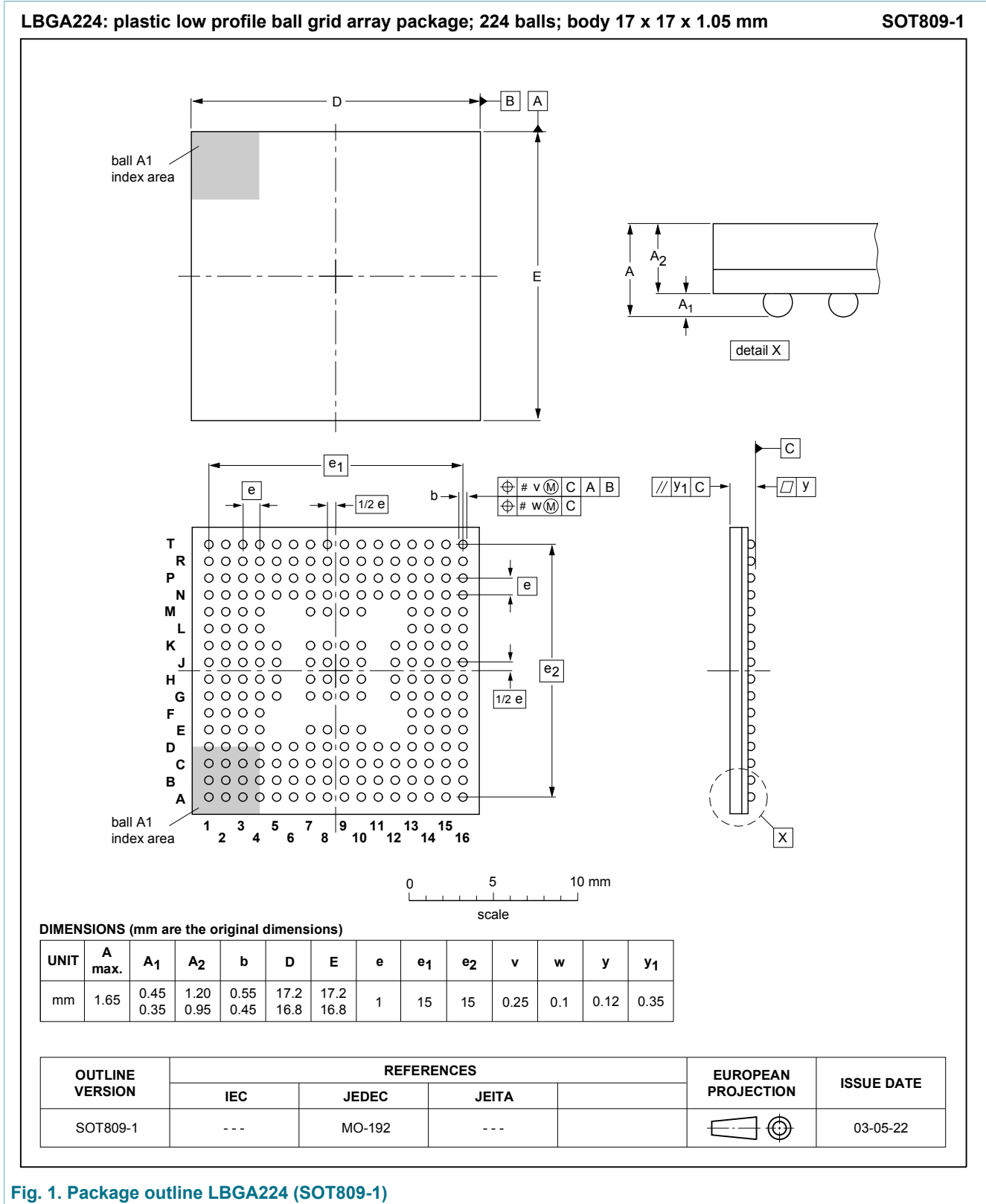


Fig. 1. Package outline LPGA224 (SOT809-1)

3. Soldering

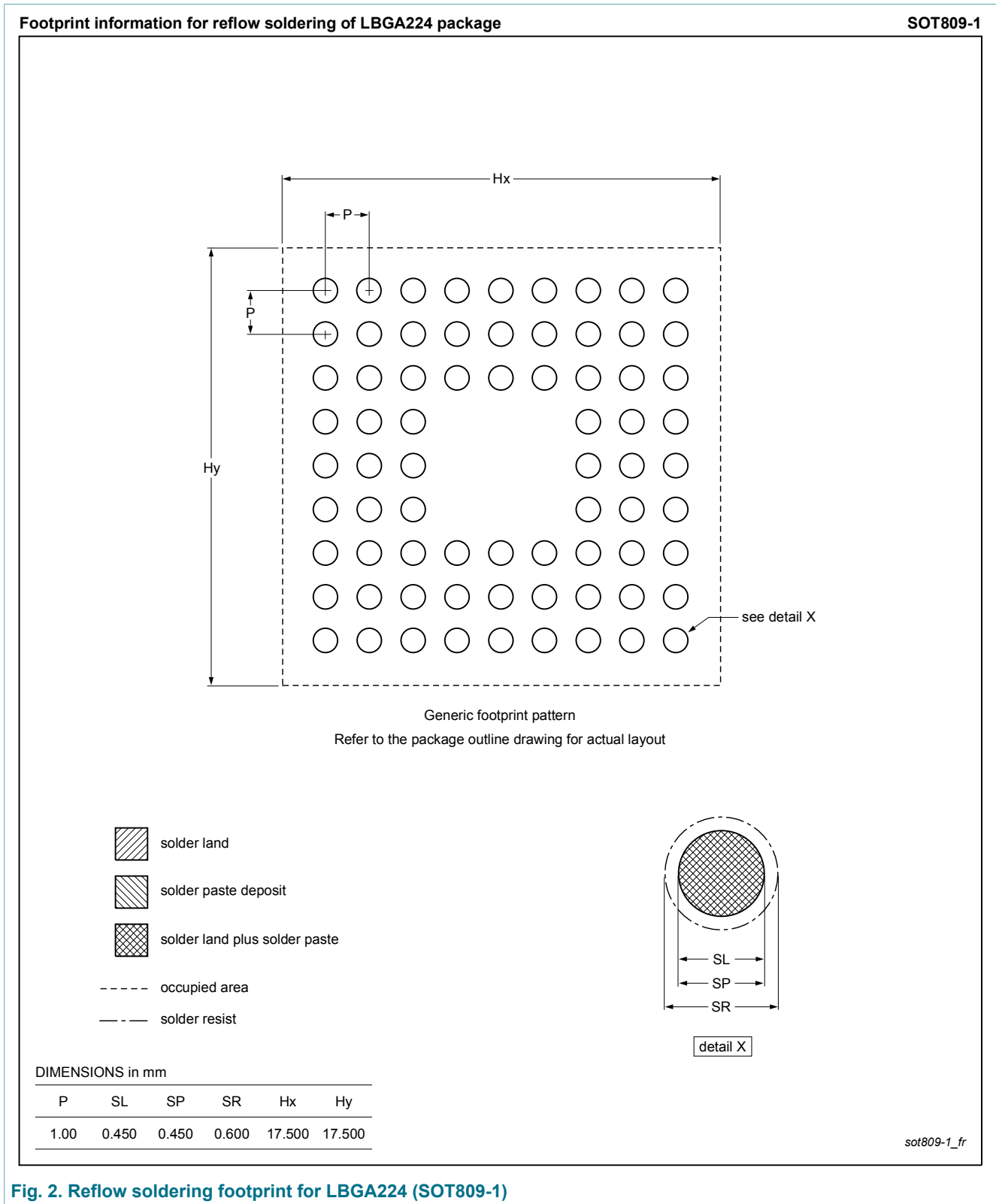


Fig. 2. Reflow soldering footprint for LBG224 (SOT809-1)

4. Legal information

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5. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Soldering.....	3
4. Legal information.....	4

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